# Flipping Bits in Memory Without Accessing Them

# **DRAM Disturbance Errors**

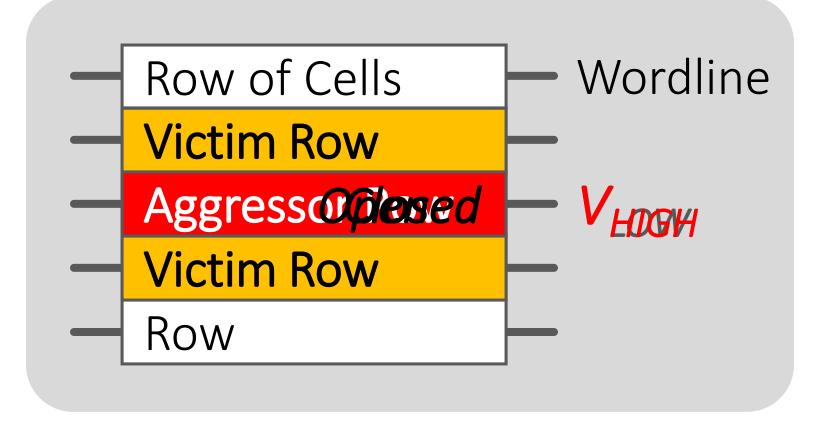
## Yoongu Kim

Ross Daly, Jeremie Kim, Chris Fallin, Ji Hye Lee, Donghyuk Lee, Chris Wilkerson, Konrad Lai, Onur Mutlu

Carnegie Mellon SAFARI



# **DRAM Chip**



Repeatedly opening and closing a row induces disturbance errors in adjacent rows

## **Quick Summary of Paper**

- We <u>expose</u> the **existence** and **prevalence** of disturbance errors in DRAM chips of today
  - 110 of 129 modules are vulnerable
  - Affects modules of 2010 vintage or later
- We <u>characterize</u> the **cause** and **symptoms** 
  - Toggling a row accelerates charge leakage in adjacent rows: *row-to-row coupling*
- We <u>prevent</u> errors using a system-level approach

   Each time a row is closed, we refresh the charge stored in its adjacent rows with a low probability

#### 1. Historical Context

#### 2. Demonstration (Real System)

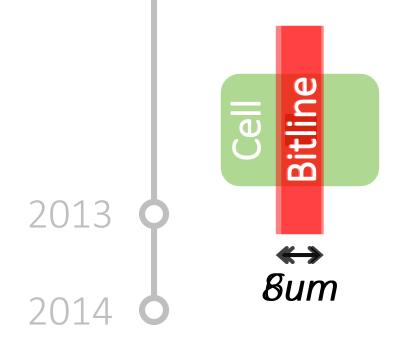
#### 3. Characterization (FPGA-Based)

#### 4. Solutions

## A Trip Down Memory Lane

1968 **Q** IBM's patent on DRAM

Intel commercializes DRAM (Intel 1103)
Suffered bitline-to-cell coupling



"... this big fat metal line with full level signals running right over the storage node (of cell)."

– **Joel Karp** (1103 Designer) Interview: Comp. History Museum

## A Trip Down Memory Lane

- 1968 IBM's patent on DRAM
- Intel commercializes DRAM (Intel 1103)
  Suffered bitline-to-cell coupling 1971 🕻

Earliest DRAM with row-to-row coupling 2010 We observe row-to-row coupling 2014 Intel's patents mention "Row Hammer"

#### Lessons from History

- Coupling in DRAM is not new
  - Leads to disturbance errors if not addressed
  - Remains a major hurdle in DRAM scaling
- Traditional efforts to contain errors
  - Design-Time: Improve circuit-level isolation
  - Production-Time: Test for disturbance errors
- Despite such efforts, disturbance errors have been slipping into the field since 2010

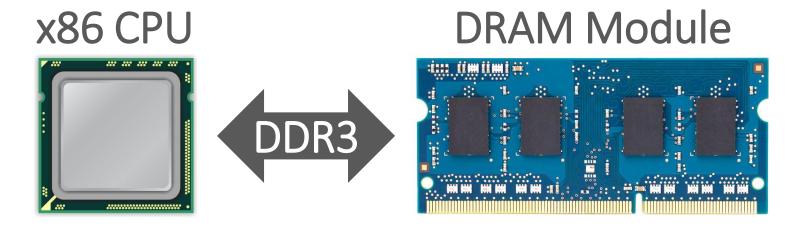
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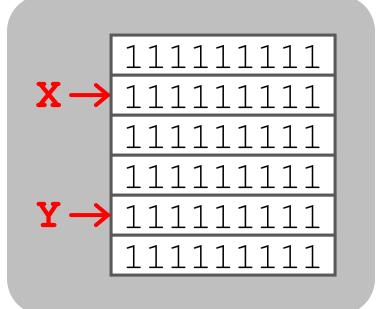
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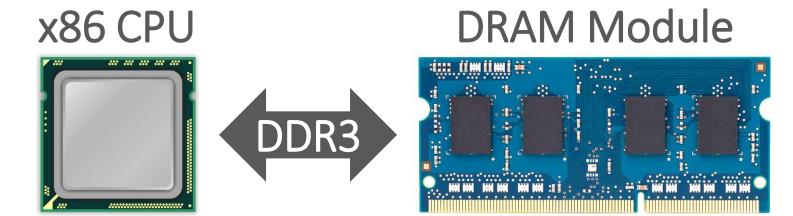
#### How to Induce Errors



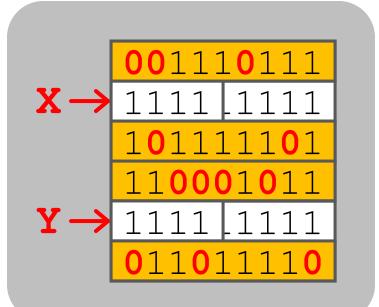
- Avoid *cache hits* Flush X from cache
- Avoid *row hits* to X
   Read Y in another row



#### How to Induce Errors



loop: mov (X), %eax mov (Y), %ebx clflush (X) clflush (Y) mfence jmp loop



## Number of Disturbance Errors

| CPU Architecture          | Errors | Access-Rate |
|---------------------------|--------|-------------|
| Intel Haswell (2013)      | 22.9K  | 12.3M/sec   |
| Intel Ivy Bridge (2012)   | 20.7K  | 11.7M/sec   |
| Intel Sandy Bridge (2011) | 16.1K  | 11.6M/sec   |
| AMD Piledriver (2012)     | 59     | 6.1M/sec    |

- In a more controlled environment, we can induce as many as ten million disturbance errors
- Disturbance errors are a serious reliability issue

## **Security Implications**

- Breach of memory protection
  - OS page (4KB) fits inside DRAM row (8KB)
  - Adjacent DRAM row  $\rightarrow$  Different OS page
- Vulnerability: disturbance attack
  - By accessing its own page, a program could corrupt pages belonging to another program
- We constructed a proof-of-concept – Using only user-level instructions

## **Mechanics of Disturbance Errors**

- Cause 1: Electromagnetic coupling
  - Toggling the wordline voltage briefly increases the voltage of adjacent wordlines
  - − Slightly opens adjacent rows → Charge leakage
- Cause 2: Conductive bridges
- Cause 3: Hot-carrier injection

#### Confirmed by at least one manufacturer

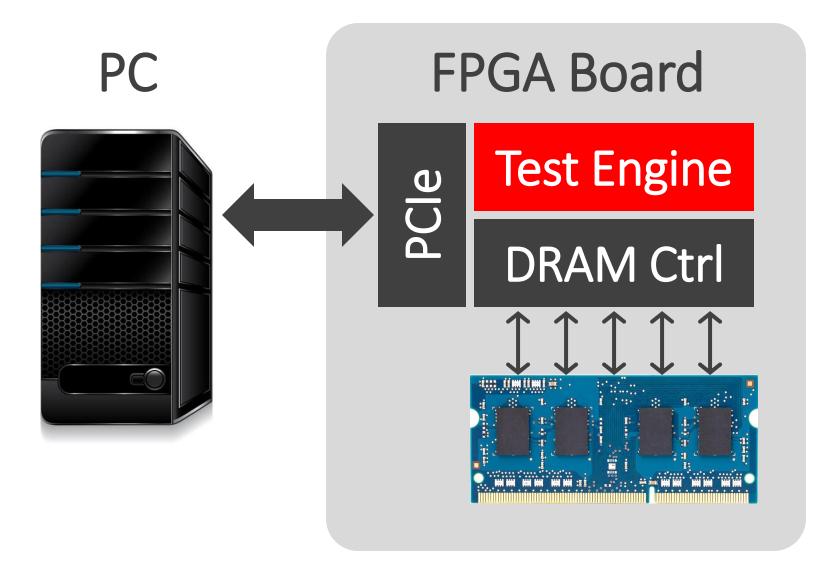
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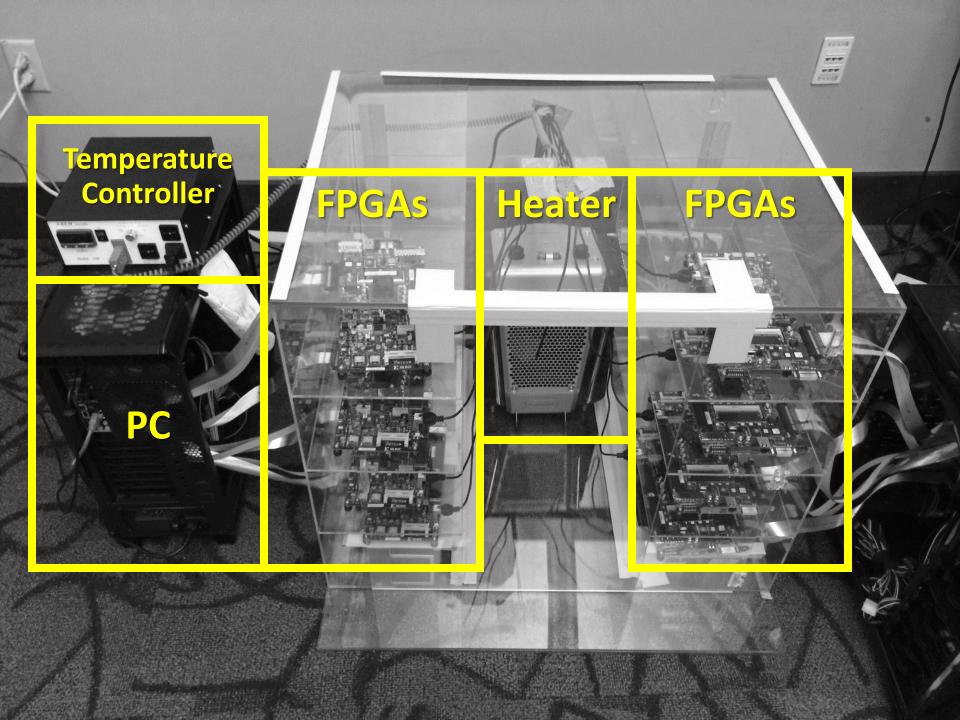
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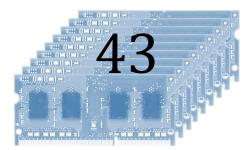
#### Infrastructure

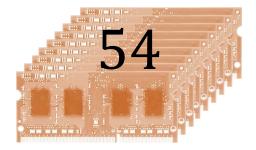


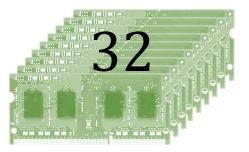


## **Tested DDR3 DRAM Modules**

#### Company A Company B Company C







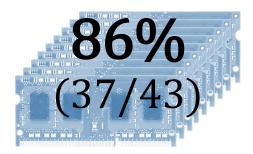
- Total: 129
- Vintage: 2008 2014
- Capacity: 512MB 2GB

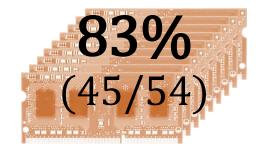
#### **Characterization Results**

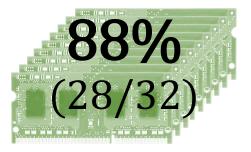
- 1. Most Modules Are at Risk
- 2. Errors vs. Vintage
- 3. Error = Charge Loss
- 4. Adjacency: Aggressor & Victim
- 5. Sensitivity Studies
- 6. Other Results in Paper

#### 1. Most Modules Are at Risk





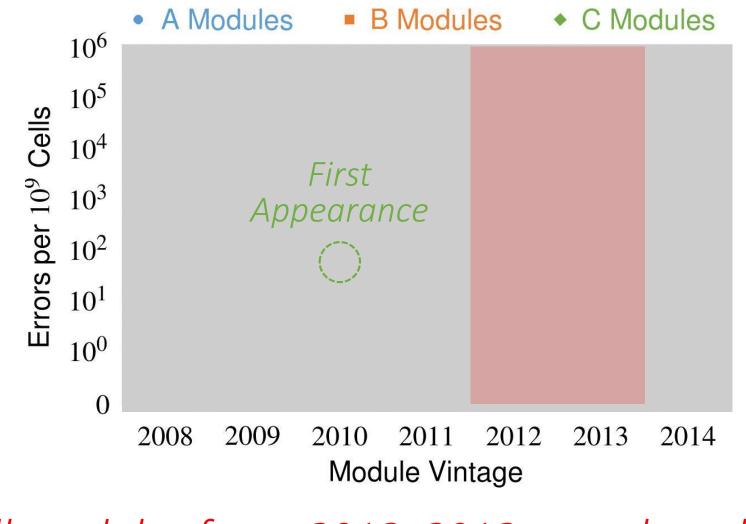




Up to 1.0×10<sup>7</sup> errors

Up to 2.7×10<sup>6</sup> errors Up to 3.3×10<sup>5</sup> errors

#### 2. Errors vs. Vintage



All modules from 2012–2013 are vulnerable

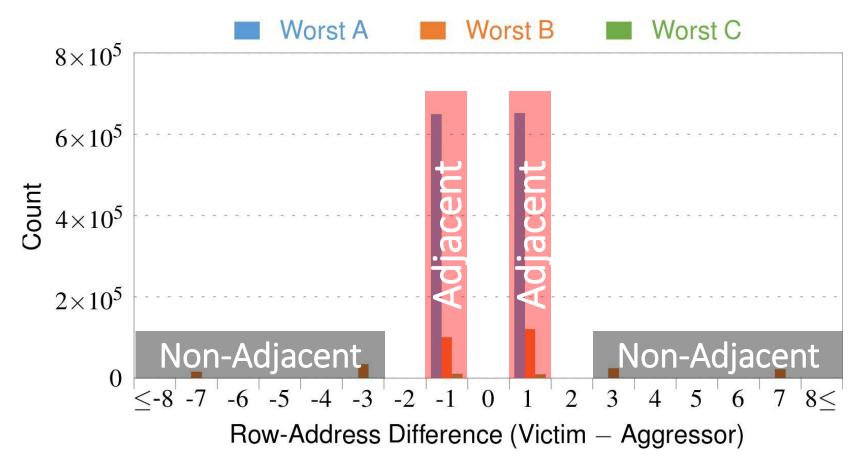
## 3. Error = Charge Loss

- Two types of errors  $- '1' \rightarrow '0'$  $- '0' \rightarrow '1'$
- A given cell suffers only one type

- Two types of cells
  - True: Charged ('1')
  - Anti: Charged ('0')
- Manufacturer's design choice
- True-cells have only '1'  $\rightarrow$  '0' errors
- Anti-cells have only '0'  $\rightarrow$  '1' errors

Errors are manifestations of charge loss

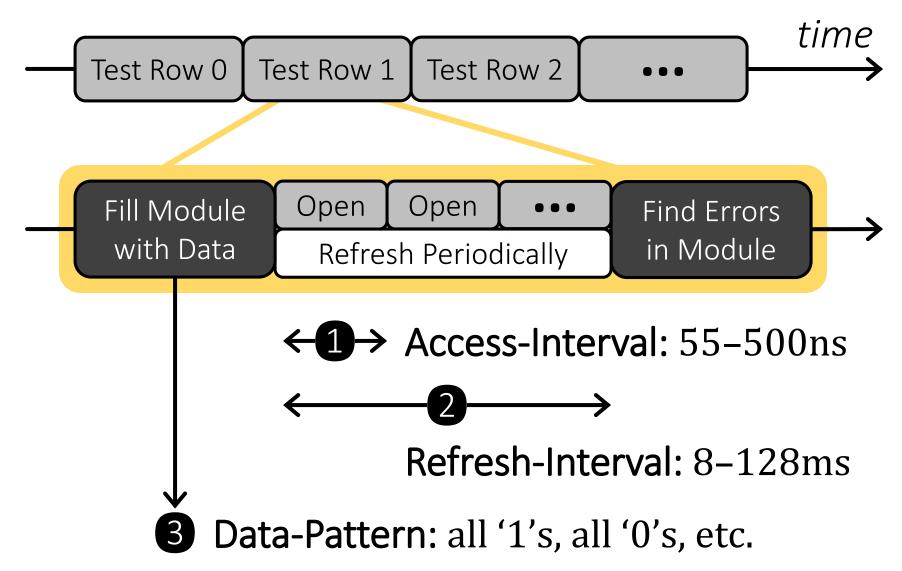
## 4. Adjacency: Aggressor & Victim



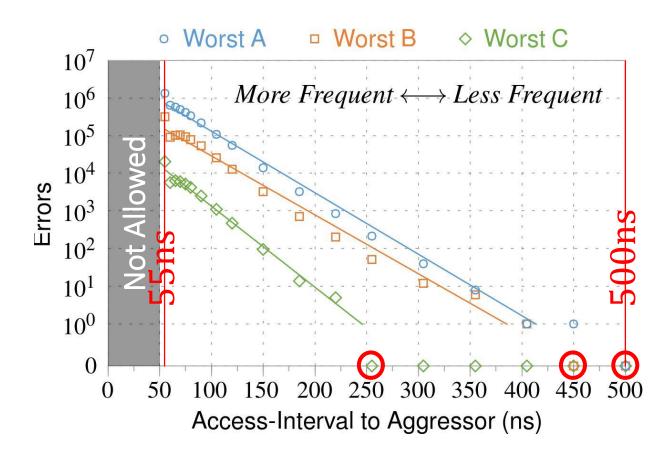
Note: For three modules with the most errors (only first bank)

Most aggressors & victims are adjacent

### 5. Sensitivity Studies



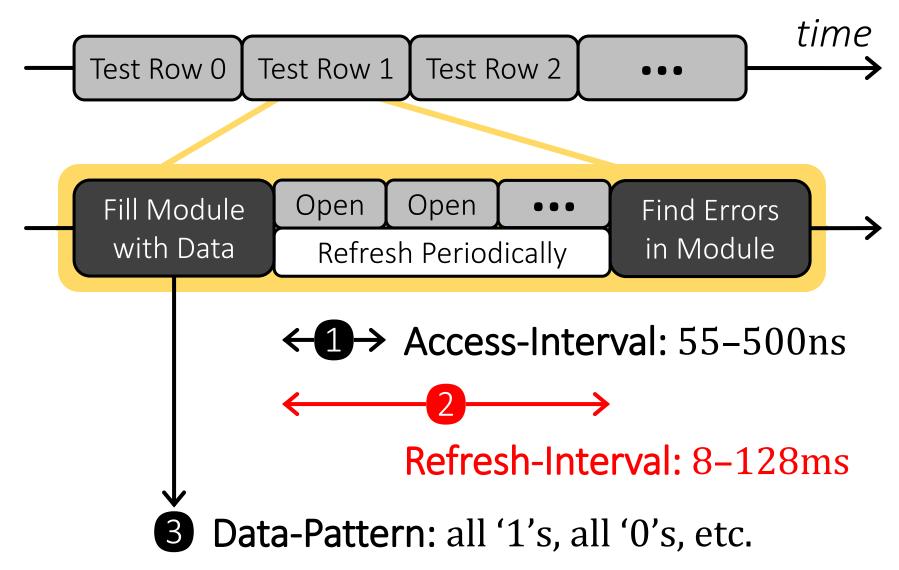
## 1 Access-Interval (Aggressor)



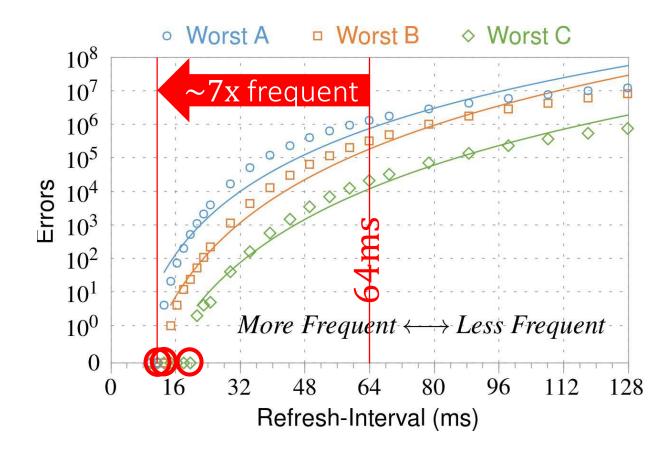
Note: For three modules with the most errors (only first bank)

*Less frequent accesses → Fewer errors* 

### 5. Sensitivity Studies



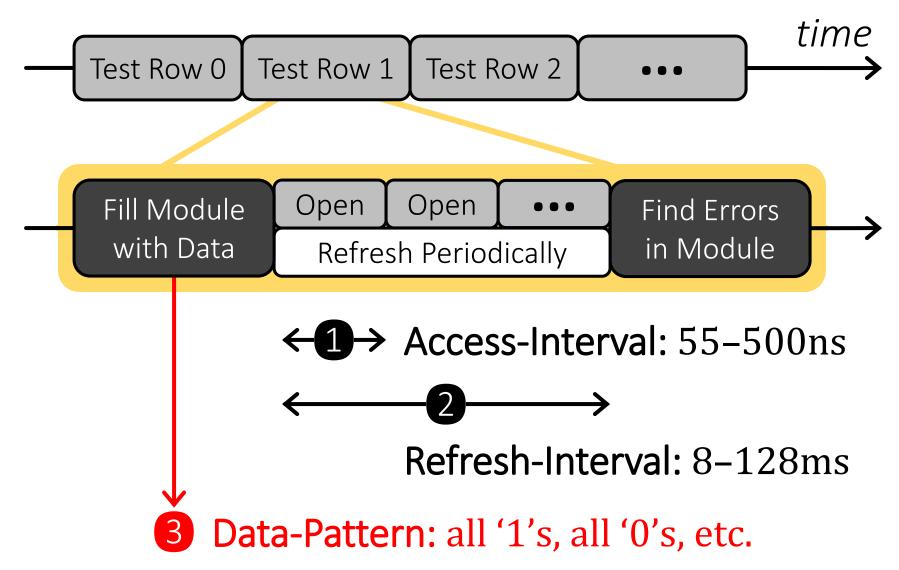
## 2 Refresh-Interval



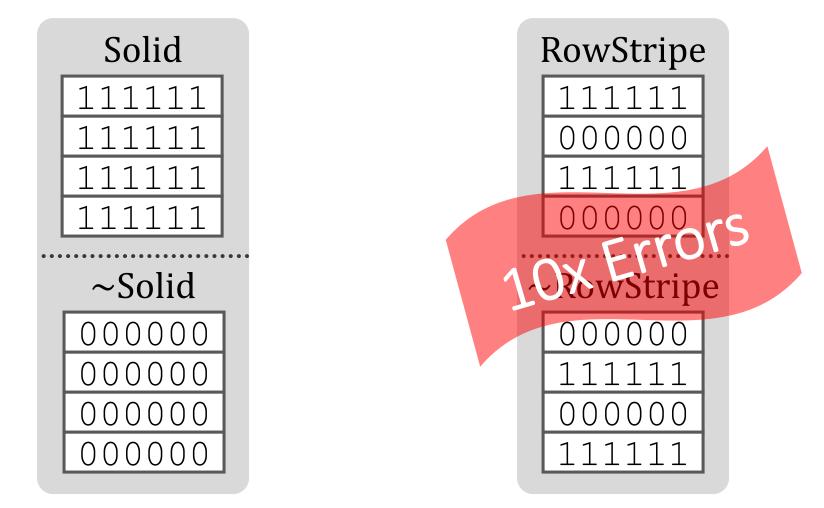
Note: Using three modules with the most errors (only first bank)

More frequent refreshes  $\rightarrow$  Fewer errors

### 5. Sensitivity Studies







Errors affected by data stored in other cells

### **Naive Solutions**

#### 1 Throttle accesses to same row

- Limit access-interval: ≥500ns
- Limit number of accesses:  $\leq 128K$  (=64ms/500ns)

#### **2** Refresh more frequently

– Shorten refresh-interval by  $\sim 7x$ 

Both naive solutions introduce significant overhead in performance and power

#### **Characterization Results**

- 1. Most Modules Are at Risk
- 2. Errors vs. Vintage
- 3. Error = Charge Loss
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- 6. Other Results in Paper

## 6. Other Results in Paper

- Victim Cells ≠ Weak Cells (i.e., leaky cells)
   Almost no overlap between them
- Errors not strongly affected by temperature
   Default temperature: 50°C
  - At 30°C and 70°C, number of errors changes <15%
- Errors are repeatable
  - Across ten iterations of testing, >70% of victim cells had errors in every iteration

## 6. Other Results in Paper (cont'd)

- As many as 4 errors per cache-line

   Simple ECC (e.g., SECDED) cannot prevent all errors
- Number of cells & rows affected by aggressor

   Victims cells per aggressor: ≤110
   Victims rows per aggressor: ≤9
- Cells affected by two aggressors on either side
  - Very small fraction of victim cells (<100) have an error when either one of the aggressors is toggled

#### 1. Historical Context

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#### 3. Characterization (FPGA-Based)



#### **Several Potential Solutions**

• Make better DRAM chips

• Refresh frequently **Power, Performance** 

• Sophisticated ECC

Cost, Power

Cost

#### • Access counters Cost, Power, Complexity

## **Our Solution**

- PARA: <u>Probabilistic Adjacent Row Activation</u>
- Key Idea
  - After closing a row, we activate (i.e., refresh) one of its neighbors with a low probability: p = 0.005
- Reliability Guarantee
  - When p=0.005, errors in one year:  $9.4 \times 10^{-14}$
  - By adjusting the value of p, we can provide an arbitrarily strong protection against errors

## Advantages of PARA

- PARA refreshes rows infrequently
  - Low power
  - Low performance-overhead
    - Average slowdown: 0.20% (for 29 benchmarks)
    - Maximum slowdown: 0.75%
- PARA is stateless
  - Low cost
  - Low complexity
- PARA is an effective and low-overhead solution to prevent disturbance errors

## Conclusion

- Disturbance errors are **widespread** in DRAM chips sold and used today
- When a row is opened repeatedly, *adjacent rows leak charge* at an accelerated rate
- We propose a *stateless solution* that prevents disturbance errors with low overhead
- Due to difficulties in DRAM scaling, new and unexpected types of failures may appear

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